

Industry Leaders Showcase ANSYS Semiconductor Solutions for Chip Design Success

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PITTSBURGH, May 12, 2016 /PRNewswire/ -- Industry-leading companies are innovating the next generation of electronic devices for high-performance computing, mobile, automotive and the Internet of Things (IoT) quicker and more efficiently – thanks to ANSYS (NASDAQ: ANSS) simulation solutions.



As the premier international conference for design and automation of electronic systems, the <u>Design Automation Conference</u> (DAC) showcases the most current developments in designs, design tools, intellectual property (IP) libraries and foundry technology support in the electronic and chip technology industry.

Designer and IP Track gives industry leaders an opportunity to share accomplishments in multiple segments of semiconductor and electronic system design processes. ANSYS customers will highlight the methodologies and flows that address complex challenges as well as how engineers are leveraging ANSYS tools to innovate the next generation of electronic devices across the industry – from automotive and IoT applications to high-performance computing and mobile devices.

"Proper design planning and sign-off for power noise, electro-migration and ESD reliability are careful design considerations in our mixed-signal IP and product design process," said Hai Lan, senior manager of SIPI at Rambus. "We look forward to the upcoming opportunity at DAC to share how Rambus is able to leverage ANSYS simulation and optimization solutions to ensure the integrity of our complex designs, making our IP more consumable."

"We are excited to see an unprecedented number of design papers from our customers at the upcoming Design Automation Conference in June," said John Lee, general manager at ANSYS. "This underscores the importance ANSYS simulation brings to the industry and the critical role it plays in the design process."

"The Designer and IP Track has become a major component of the overall DAC Technical Program and we are pleased with the quality and the overall number of submissions received for DAC 2016," said Chuck Alpert, general chair, 53rd DAC. "It is with support of companies like ANSYS, customers and users in the design community that this track keeps growing each year."

ANSYS will be featured at DAC in booth 1449 in June 6-8 in Austin, Texas.

About ANSYS, Inc.

ANSYS is the global leader in engineering simulation. We bring clarity and insight to our customer's most complex design challenges through the broadest portfolio of fast, accurate and reliable simulation tools. Our technology enables organizations in all industries to imagine high-quality, innovative product designs that are sustainable and have an accelerated time to market. Founded in 1970, ANSYS employs almost 3000 professionals, more than 700 of them with PhDs in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, embedded software, system simulation and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales and development locations throughout the world with a network of channel partners in 40+ countries. Visit http://www.ansys.com for more information.

ANSYS also has a strong presence on the major social channels. To join the simulation conversation, please visit: www.ansys.com/Social@ANSYS

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